LAYER 1 - TOP COMPONENTS
LAYER 2 - RAW POWER & ANALOG 2.5V PLANES
LAYER 3 - SIGNALS (100 OHM DIFF PAIRS)
11. TOLERANCES:
- Bow and twist shall not exceed 0.5%.
- Conductor width and spacing shall be within 0.001 inch of Gerber file.
- Final PWB thickness shall be as shown in stack-up detail.
- Surface mount pads shall be flat and shall not extend more than 0.001 inch.

12. THROUGH HOLES:
- Hole sizes in drill chart are in MLS and specify finished diameter.
- Layer to layer registration shall be within 0.003 inch.
- Hole location shall be within 0.004 radius of true position (RT).
- All holes shall be on first drill second drill is not permitted.
- Tolerance for component lead holes is +/- 0.003 inch.
- Tolerance for unplated holes is +0.002 / -0.002 inch.
- Tolerance for via holes is +0.002 / -0.010 inch.

13. CONTROLLED IMPEDANCE: 100 OHMS +/- 10% ON ALL LAYERS.
14. FILL ALL VIAS.
15. CROSS SECTION CUT REQUIRED.
16. PLATE 5–10 MICROINCH OF SOFT GOLD OVER 15 MICRON NICKEL.

(LAYER 6) 1 OZ. COPPER
(LAYER 7) 1/2 OZ. COPPER
(LAYER 8) 1 OZ. COPPER
(LAYER 9) 1 OZ. COPPER
(LAYER 10) 1/2 OZ. STARTING COPPER

SOLDERMASK (BOTTOM SIDE)
SILKSCREEN (BOTTOM SIDE)